

# **Europe Advanced Packaging Market By Type (Flip-Chip Ball Grid Array, Flip Chip CSP, Wafer Level CSP, 2),5D/3D and others), By End User (Consumer Electronics, Automotive, Industrial, Aerospace & Defense, Healthcare & Life Sciences and Others), By Country, Industry Analysis and Forecast, 2020 - 2026**

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## **Abstracts**

The Europe Advanced Packaging Market would witness market growth of 12.3% CAGR during the forecast period (2020-2026).

With rapid growth in the advanced packaging market, particularly in wafer level packaging, together with increased demand for smartphones and devices and the Internet of Things (IoT), advanced packaging suppliers are developing processes and ways to reduce the overall cost of advanced packaging and ensure maximum operational efficiency.

In recent times, innovative packaging is primarily used for high-end products and for niche-related applications such as wafer and die processing due to high operating costs. Different integrated circuits (ICs) have various packaging requirements that provide growth opportunities for advanced packaging over traditional packaging processes. Furthermore, advanced packaging is expected to offer higher capabilities than conventional packaging solutions, which are expected to provide lucrative opportunities for advanced packaging market trends in the coming years.

The demand for compact electronic devices has increased in almost every sector, be it communication equipment, automotive, industrial or healthcare equipment. This trend has prompted semiconductor IC manufacturers to increase R&D investment in order to reduce the size and improve the output of ICs. This led to the advent of MEMS and 3D IC chips. In addition, over the decades, ICs have often been more dense due to the growing number of interconnects and transistors requiring better deposition and

patterning.

Based on Type, the market is segmented into Flip-Chip Ball Grid Array, Flip Chip CSP, Wafer Level CSP, 2.5D/3D and Others. Based on End User, the market is segmented into Consumer Electronics, Automotive, Industrial, Aerospace & Defense, Healthcare & Life Sciences and Others. Based on countries, the market is segmented into Germany, UK, France, Russia, Spain, Italy, and Rest of Europe.

The market research report covers the analysis of key stake holders of the market. Key companies profiled in the report include Qualcomm, Inc., Intel Corporation, IBM Corporation, Texas Instruments, Inc., Analog Devices, Inc., Renesas Electronics Corporation, Samsung Electronics Co., Ltd. (Samsung Group), Amkor Technology, Inc., Brewer Science, Inc., and MICROCHIP Technology, Inc.

Scope of the Study

Market Segmentation:

By Type

Flip-Chip Ball Grid Array

Flip Chip CSP

Wafer Level CSP

2.5D/3D

Others

By End User

Consumer Electronics

Automotive

Industrial

Aerospace & Defense

Healthcare & Life Sciences

Others

#### By Country

Germany

UK

France

Russia

Spain

Italy

Rest of Europe

#### Companies Profiled

Qualcomm, Inc.

Intel Corporation

IBM Corporation

Texas Instruments, Inc.

Analog Devices, Inc.

Renesas Electronics Corporation

Samsung Electronics Co., Ltd. (Samsung Group)

Amkor Technology, Inc.

Brewer Science, Inc.

Microchip Technology, Inc.

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## Contents

### CHAPTER 1. MARKET SCOPE & METHODOLOGY

- 1.1 Market Definition
- 1.2 Objectives
- 1.3 Market Scope
- 1.4 Segmentation
  - 1.4.1 Europe Advanced Packaging Market, by Type
  - 1.4.2 Europe Advanced Packaging Market, by End User
  - 1.4.3 Europe Advanced Packaging Market, by Country
- 1.5 Methodology for the research

### CHAPTER 2. MARKET OVERVIEW

- 2.1 Introduction
  - 2.1.1 Overview
  - 2.1.2 Executive Summary
  - 2.1.3 Market Composition and Scenario
- 2.2 Key Factors Impacting the Market
  - 2.2.1 Market Drivers
  - 2.2.2 Market Restraints

### CHAPTER 3. COMPETITION ANALYSIS - GLOBAL

- 3.1 KBV Cardinal Matrix
- 3.2 Recent Industry Wide Strategic Developments
  - 3.2.1 Partnerships, Collaborations and Agreements
  - 3.2.2 Product Launches and Product Expansions
  - 3.2.3 Geographical Expansions
  - 3.2.4 Mergers & Acquisitions
- 3.3 Top Winning Strategies
  - 3.3.1 Key Leading Strategies: Percentage Distribution (2016-2020)
  - 3.3.2 Key Strategic Move: (Partnerships, Collaborations, and Agreements : 2016, Jan – 2019,Dec) Leading Players

### CHAPTER 4. EUROPE ADVANCED PACKAGING MARKET BY TYPE

- 4.1 Europe Advanced Packaging Flip-Chip Ball Grid Array Market by Country

*Europe Advanced Packaging Market By Type (Flip-Chip Ball Grid Array, Flip Chip CSP, Wafer Level CSP, 2),5D/3D...*

- 4.2 Europe Advanced Packaging Flip Chip CSP Market by Country
- 4.3 Europe Advanced Packaging Wafer Level CSP Market by Country
- 4.4 Europe Advanced Packaging 2.5D/3D Market by Country
- 4.5 Europe Other Type Advanced Packaging Market by Country

## **CHAPTER 5. EUROPE ADVANCED PACKAGING MARKET BY END USER**

- 5.1 Europe Consumer Electronics Advanced Packaging Market by Country
- 5.2 Europe Automotive Advanced Packaging Market by Country
- 5.3 Europe Industrial Advanced Packaging Market by Country
- 5.4 Europe Aerospace & Defense Advanced Packaging Market by Country
- 5.5 Europe Healthcare & Life Sciences Advanced Packaging Market by Country
- 5.6 Europe Others Advanced Packaging Market by Country

## **CHAPTER 6. EUROPE ADVANCED PACKAGING MARKET BY COUNTRY**

- 6.1 Germany Advanced Packaging Market
  - 6.1.1 Germany Advanced Packaging Market by Type
  - 6.1.2 Germany Advanced Packaging Market by End User
- 6.2 UK Advanced Packaging Market
  - 6.2.1 UK Advanced Packaging Market by Type
  - 6.2.2 UK Advanced Packaging Market by End User
- 6.3 France Advanced Packaging Market
  - 6.3.1 France Advanced Packaging Market by Type
  - 6.3.2 France Advanced Packaging Market by End User
- 6.4 Russia Advanced Packaging Market
  - 6.4.1 Russia Advanced Packaging Market by Type
  - 6.4.2 Russia Advanced Packaging Market by End User
- 6.5 Spain Advanced Packaging Market
  - 6.5.1 Spain Advanced Packaging Market by Type
  - 6.5.2 Spain Advanced Packaging Market by End User
- 6.6 Italy Advanced Packaging Market
  - 6.6.1 Italy Advanced Packaging Market by Type
  - 6.6.2 Italy Advanced Packaging Market by End User
- 6.7 Rest of Europe Advanced Packaging Market
  - 6.7.1 Rest of Europe Advanced Packaging Market by Type
  - 6.7.2 Rest of Europe Advanced Packaging Market by End User

## **CHAPTER 7. COMPANY PROFILES**

## 7.1 Qualcomm, Inc.

### 7.1.1 Company Overview

### 7.1.1 Financial Analysis

### 7.1.2 Segmental and Regional Analysis

### 7.1.3 Research & Development Expense

### 7.1.4 Recent strategies and developments:

#### 7.1.4.1 Partnerships, Collaborations, and Agreements:

#### 7.1.4.2 Geographical Expansions:

### 7.1.5 SWOT Analysis

## 7.2 Intel Corporation

### 7.2.1 Company Overview

### 7.2.2 Financial Analysis

### 7.2.3 Segmental and Regional Analysis

### 7.2.4 Research & Development Expenses

### 7.2.5 Recent strategies and developments:

#### 7.2.5.1 Partnerships, Collaborations, and Agreements:

#### 7.2.5.2 Product Launches and Product Expansions:

### 7.2.6 SWOT Analysis

## 7.3 IBM Corporation

### 7.3.1 Company Overview

### 7.3.2 Financial Analysis

### 7.3.3 Regional & Segmental Analysis

### 7.3.4 Research & Development Expenses

### 7.3.5 Recent strategies and developments:

#### 7.3.5.1 Partnerships, Collaborations, and Agreements:

### 7.3.6 SWOT Analysis

## 7.4 Texas Instruments, Inc.

### 7.4.1 Company Overview

### 7.4.2 Financial Analysis

### 7.4.3 Segmental and Regional Analysis

### 7.4.4 Research & Development Expense

### 7.4.5 Recent strategies and developments:

#### 7.4.5.1 Product Launches and Product Expansions:

### 7.4.6 SWOT Analysis

## 7.5 Analog Devices, Inc.

### 7.5.1 Company Overview

### 7.5.2 Financial Analysis

### 7.5.3 Segmental and Regional Analysis

- 7.5.4 Research & Development Expenses
- 7.5.5 SWOT Analysis
- 7.6 Renesas Electronics Corporation
  - 7.6.1 Company Overview
  - 7.6.2 Financial Analysis
  - 7.6.3 Segmental and Regional Analysis
  - 7.6.4 Research & Development Expense
  - 7.6.5 Recent strategies and developments:
    - 7.6.5.1 Product Launches and Product Expansions:
    - 7.6.5.2 Acquisition and Mergers:
- 7.7 Samsung Electronics Co., Ltd. (Samsung Group)
  - 7.7.1 Company Overview
  - 7.7.2 Financial Analysis
  - 7.7.3 Segmental and Regional Analysis
  - 7.7.4 Research & Development Expense
  - 7.7.5 Recent strategies and developments:
    - 7.7.5.1 Partnerships, Collaborations, and Agreements:
    - 7.7.5.2 Geographical Expansions:
  - 7.7.6 SWOT Analysis
- 7.8 Amkor Technology, Inc.
  - 7.8.1 Company Overview
  - 7.8.2 Financial Analysis
  - 7.8.3 Regional Analysis
  - 7.8.4 Research & Development Expense
  - 7.8.5 Recent strategies and developments:
    - 7.8.5.1 Partnerships, Collaborations, and Agreements:
    - 7.8.5.2 Acquisition and Mergers:
- 7.9 Brewer Science, Inc.
  - 7.9.1 Company Overview
  - 7.9.2 Recent strategies and developments:
    - 7.9.2.1 Product Launches and Product Expansions:
- 7.1 Microchip Technology, Inc.
  - 7.10.1 Company overview
  - 7.10.2 Financial Analysis
  - 7.10.3 Segmental and Regional Analysis
  - 7.10.4 Research & Development Expenses
  - 7.10.5 Recent strategies and developments:
    - 7.10.5.1 Geographical Expansions:



## List Of Tables

### LIST OF TABLES

TABLE 1 EUROPE ADVANCED PACKAGING MARKET, 2016 - 2019, USD MILLION

TABLE 2 EUROPE ADVANCED PACKAGING MARKET, 2020 - 2026, USD MILLION

TABLE 3 PARTNERSHIPS, COLLABORATIONS AND AGREEMENTS– ADVANCED PACKAGING MARKET

TABLE 4 PRODUCT LAUNCHES AND PRODUCT EXPANSIONS– ADVANCED PACKAGING MARKET

TABLE 5 GEOGRAPHICAL EXPANSIONS– ADVANCED PACKAGING MARKET

TABLE 6 MERGERS & ACQUISITIONS – ADVANCED PACKAGING MARKET

TABLE 7 EUROPE ADVANCED PACKAGING MARKET BY TYPE, 2016 - 2019, USD MILLION

TABLE 8 EUROPE ADVANCED PACKAGING MARKET BY TYPE, 2020 - 2026, USD MILLION

TABLE 9 EUROPE ADVANCED PACKAGING FLIP-CHIP BALL GRID ARRAY MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 10 EUROPE ADVANCED PACKAGING FLIP-CHIP BALL GRID ARRAY MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 11 EUROPE ADVANCED PACKAGING FLIP CHIP CSP MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 12 EUROPE ADVANCED PACKAGING FLIP CHIP CSP MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 13 EUROPE ADVANCED PACKAGING WAFER LEVEL CSP MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 14 EUROPE ADVANCED PACKAGING WAFER LEVEL CSP MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 15 EUROPE ADVANCED PACKAGING 2.5D/3D MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 16 EUROPE ADVANCED PACKAGING 2.5D/3D MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 17 EUROPE OTHER TYPE ADVANCED PACKAGING MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 18 EUROPE OTHER TYPE ADVANCED PACKAGING MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 19 EUROPE ADVANCED PACKAGING MARKET BY END USER, 2016 - 2019, USD MILLION

TABLE 20 EUROPE ADVANCED PACKAGING MARKET BY END USER, 2020 - 2026,

USD MILLION

TABLE 21 EUROPE CONSUMER ELECTRONICS ADVANCED PACKAGING MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 22 EUROPE CONSUMER ELECTRONICS ADVANCED PACKAGING MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 23 EUROPE AUTOMOTIVE ADVANCED PACKAGING MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 24 EUROPE AUTOMOTIVE ADVANCED PACKAGING MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 25 EUROPE INDUSTRIAL ADVANCED PACKAGING MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 26 EUROPE INDUSTRIAL ADVANCED PACKAGING MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 27 EUROPE AEROSPACE & DEFENSE ADVANCED PACKAGING MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 28 EUROPE AEROSPACE & DEFENSE ADVANCED PACKAGING MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 29 EUROPE HEALTHCARE & LIFE SCIENCES ADVANCED PACKAGING MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 30 EUROPE HEALTHCARE & LIFE SCIENCES ADVANCED PACKAGING MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 31 EUROPE OTHERS ADVANCED PACKAGING MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 32 EUROPE OTHERS ADVANCED PACKAGING MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 33 EUROPE ADVANCED PACKAGING MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 34 EUROPE ADVANCED PACKAGING MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 35 GERMANY ADVANCED PACKAGING MARKET, 2016 - 2019, USD MILLION

TABLE 36 GERMANY ADVANCED PACKAGING MARKET, 2020 - 2026, USD MILLION

TABLE 37 GERMANY ADVANCED PACKAGING MARKET BY TYPE, 2016 - 2019, USD MILLION

TABLE 38 GERMANY ADVANCED PACKAGING MARKET BY TYPE, 2020 - 2026, USD MILLION

TABLE 39 GERMANY ADVANCED PACKAGING MARKET BY END USER, 2016 - 2019, USD MILLION

TABLE 40 GERMANY ADVANCED PACKAGING MARKET BY END USER, 2020 - 2026, USD MILLION

TABLE 41 UK ADVANCED PACKAGING MARKET, 2016 - 2019, USD MILLION

TABLE 42 UK ADVANCED PACKAGING MARKET, 2020 - 2026, USD MILLION

TABLE 43 UK ADVANCED PACKAGING MARKET BY TYPE, 2016 - 2019, USD MILLION

TABLE 44 UK ADVANCED PACKAGING MARKET BY TYPE, 2020 - 2026, USD MILLION

TABLE 45 UK ADVANCED PACKAGING MARKET BY END USER, 2016 - 2019, USD MILLION

TABLE 46 UK ADVANCED PACKAGING MARKET BY END USER, 2020 - 2026, USD MILLION

TABLE 47 FRANCE ADVANCED PACKAGING MARKET, 2016 - 2019, USD MILLION

TABLE 48 FRANCE ADVANCED PACKAGING MARKET, 2020 - 2026, USD MILLION

TABLE 49 FRANCE ADVANCED PACKAGING MARKET BY TYPE, 2016 - 2019, USD MILLION

TABLE 50 FRANCE ADVANCED PACKAGING MARKET BY TYPE, 2020 - 2026, USD MILLION

TABLE 51 FRANCE ADVANCED PACKAGING MARKET BY END USER, 2016 - 2019, USD MILLION

TABLE 52 FRANCE ADVANCED PACKAGING MARKET BY END USER, 2020 - 2026, USD MILLION

TABLE 53 RUSSIA ADVANCED PACKAGING MARKET, 2016 - 2019, USD MILLION

TABLE 54 RUSSIA ADVANCED PACKAGING MARKET, 2020 - 2026, USD MILLION

TABLE 55 RUSSIA ADVANCED PACKAGING MARKET BY TYPE, 2016 - 2019, USD MILLION

TABLE 56 RUSSIA ADVANCED PACKAGING MARKET BY TYPE, 2020 - 2026, USD MILLION

TABLE 57 RUSSIA ADVANCED PACKAGING MARKET BY END USER, 2016 - 2019, USD MILLION

TABLE 58 RUSSIA ADVANCED PACKAGING MARKET BY END USER, 2020 - 2026, USD MILLION

TABLE 59 SPAIN ADVANCED PACKAGING MARKET, 2016 - 2019, USD MILLION

TABLE 60 SPAIN ADVANCED PACKAGING MARKET, 2020 - 2026, USD MILLION

TABLE 61 SPAIN ADVANCED PACKAGING MARKET BY TYPE, 2016 - 2019, USD MILLION

TABLE 62 SPAIN ADVANCED PACKAGING MARKET BY TYPE, 2020 - 2026, USD MILLION

TABLE 63 SPAIN ADVANCED PACKAGING MARKET BY END USER, 2016 - 2019,

USD MILLION

TABLE 64 SPAIN ADVANCED PACKAGING MARKET BY END USER, 2020 - 2026,  
USD MILLION

TABLE 65 ITALY ADVANCED PACKAGING MARKET, 2016 - 2019, USD MILLION

TABLE 66 ITALY ADVANCED PACKAGING MARKET, 2020 - 2026, USD MILLION

TABLE 67 ITALY ADVANCED PACKAGING MARKET BY TYPE, 2016 - 2019, USD  
MILLION

TABLE 68 ITALY ADVANCED PACKAGING MARKET BY TYPE, 2020 - 2026, USD  
MILLION

TABLE 69 ITALY ADVANCED PACKAGING MARKET BY END USER, 2016 - 2019,  
USD MILLION

TABLE 70 ITALY ADVANCED PACKAGING MARKET BY END USER, 2020 - 2026,  
USD MILLION

TABLE 71 REST OF EUROPE ADVANCED PACKAGING MARKET, 2016 - 2019, USD  
MILLION

TABLE 72 REST OF EUROPE ADVANCED PACKAGING MARKET, 2020 - 2026, USD  
MILLION

TABLE 73 REST OF EUROPE ADVANCED PACKAGING MARKET BY TYPE, 2016 -  
2019, USD MILLION

TABLE 74 REST OF EUROPE ADVANCED PACKAGING MARKET BY TYPE, 2020 -  
2026, USD MILLION

TABLE 75 REST OF EUROPE ADVANCED PACKAGING MARKET BY END USER,  
2016 - 2019, USD MILLION

TABLE 76 REST OF EUROPE ADVANCED PACKAGING MARKET BY END USER,  
2020 - 2026, USD MILLION

TABLE 77 KEY INFORMATION – QUALCOMM, INC.

TABLE 78 KEY INFORMATION – INTEL CORPORATION

TABLE 79 KEY INFORMATION – IBM CORPORATION

TABLE 80 KEY INFORMATION – TEXAS INSTRUMENTS, INC.

TABLE 81 KEY INFORMATION – ANALOG DEVICES, INC.

TABLE 82 KEY INFORMATION – RENESAS ELECTRONICS CORPORATION

TABLE 83 KEY INFORMATION –SAMSUNG ELECTRONICS CO., LTD.

TABLE 84 KEY INFORMATION – AMKOR TECHNOLOGY, INC.

TABLE 85 KEY INFORMATION – BREWER SCIENCE, INC.

TABLE 86 KEY INFORMATION – MICROCHIP TECHNOLOGY, INC.

## List Of Figures

### LIST OF FIGURES

FIG 1 METHODOLOGY FOR THE RESEARCH

FIG 2 KBV CARDINAL MATRIX

FIG 3 KEY LEADING STRATEGIES: PERCENTAGE DISTRIBUTION (2016-2020)

FIG 4 KEY STRATEGIC MOVE: (PARTNERSHIPS, COLLABORATIONS, AND AGREEMENTS : 2016, JAN – 2019,DEC) LEADING PLAYERS

FIG 5 RECENT STRATEGIES AND DEVELOPMENTS: QUALCOMM, INC.

FIG 6 SWOT ANALYSIS: QUALCOMM, INC.

FIG 7 RECENT STRATEGIES AND DEVELOPMENTS: INTEL CORPORATION

FIG 8 SWOT ANALYSIS: INTEL CORPORATION

FIG 9 SWOT ANALYSIS: IBM CORPORATION

FIG 10 SWOT ANALYSIS: TEXAS INSTRUMENTS, INC.

FIG 11 SWOT ANALYSIS: ANALOG DEVICES, INC.

FIG 12 RECENT STRATEGIES AND DEVELOPMENTS: RENESAS ELECTRONICS CORPORATION

FIG 13 RECENT STRATEGIES AND DEVELOPMENTS: SAMSUNG ELECTRONICS CO., LTD.

FIG 14 SWOT ANALYSIS: SAMSUNG ELECTRONICS CO. LTD.

FIG 15 RECENT STRATEGIES AND DEVELOPMENTS: AMKOR TECHNOLOGY, INC.

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